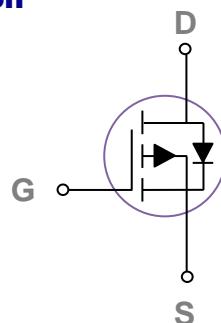
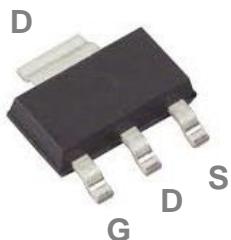


General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOT223 Pin Configuration



BVDSS	RDS(ON)	ID
-60V	105mΩ	-3.2A

Features

- -60V, -3.2A, RDS(ON) = 105mΩ@VGS = -10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- Motor Drive
- Power Tools
- LED Lighting

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-60	V
V _{Gs}	Gate-Source Voltage	± 20	V
I _D	Drain Current – Continuous ($T_A=25^\circ\text{C}$)	-3.2	A
	Drain Current – Continuous ($T_A=70^\circ\text{C}$)	-2.56	A
I _{DM}	Drain Current – Pulsed ¹	-12.8	A
EAS	Single Pulse Avalanche Energy ²	25	mJ
I _{AS}	Single Pulse Avalanche Current ²	-18	A
P _D	Power Dissipation ($T_A=25^\circ\text{C}$)	2.02	W
	Power Dissipation – Derate above 25°C	0.02	W/°C
T _{STG}	Storage Temperature Range	-50 to 150	°C
T _J	Operating Junction Temperature Range	-50 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	23	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-60	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	---	-0.05	---	$^\circ\text{C}$
I_{DS}	Drain-Source Leakage Current	$V_{\text{DS}}=-60\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{\text{DS}}=-48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-3\text{A}$	---	87	105	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-2\text{A}$	---	120	145	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
			---	3	---	mV/C
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$, $I_{\text{D}}=-3\text{A}$	---	5.5	---	S

Dynamic and switching Characteristics

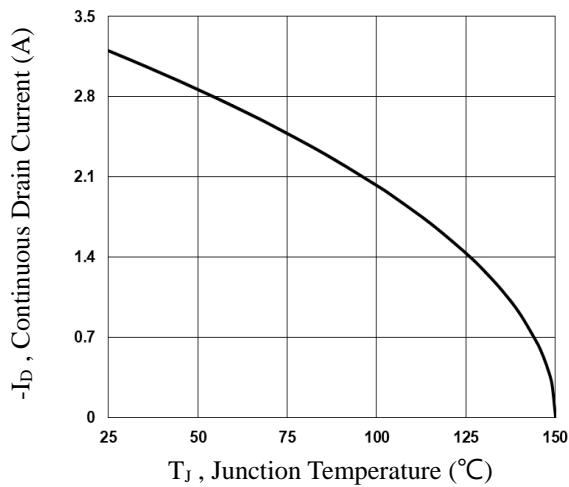
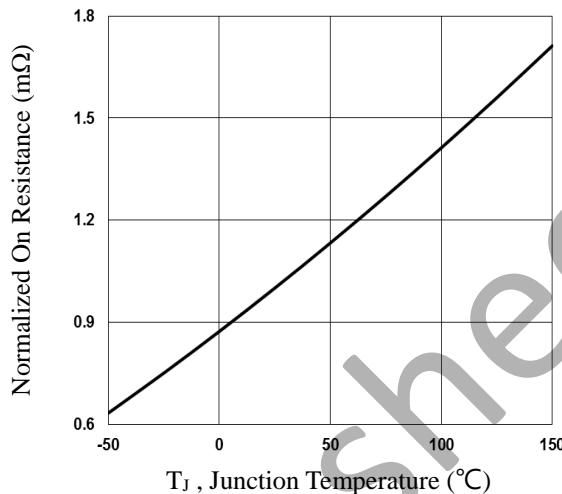
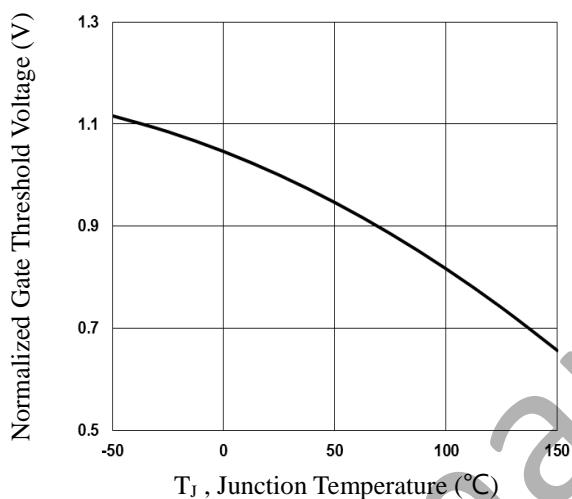
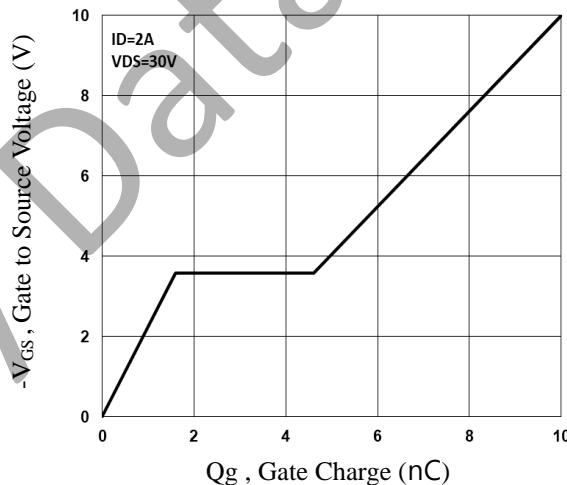
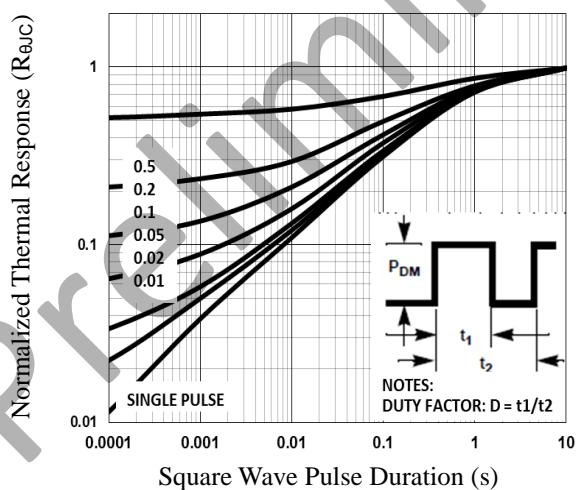
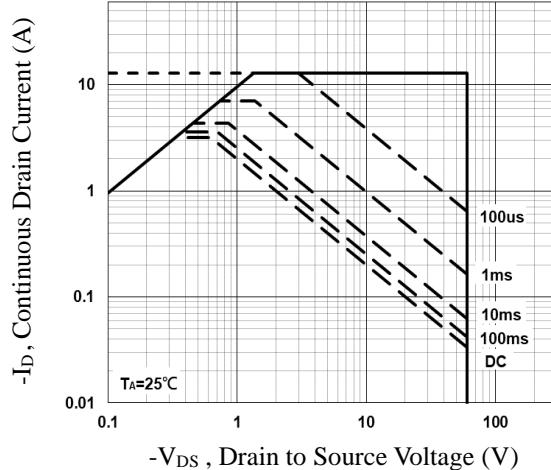
Q_g	Total Gate Charge ^{3, 4}	$V_{\text{DS}}=-30\text{V}$, $V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-2\text{A}$	---	10	15	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	1.6	3.2	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	3	6	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{3, 4}	$V_{\text{DD}}=-30\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_{\text{G}}=6\Omega$	---	8	16	ns
T_r	Rise Time ^{3, 4}		---	15.4	30	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{3, 4}		---	42.8	80	
T_f	Fall Time ^{3, 4}		---	8.4	16	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-30\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	785	1300	pF
C_{oss}	Output Capacitance		---	175	300	
C_{rss}	Reverse Transfer Capacitance		---	112	220	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	36	---	Ω

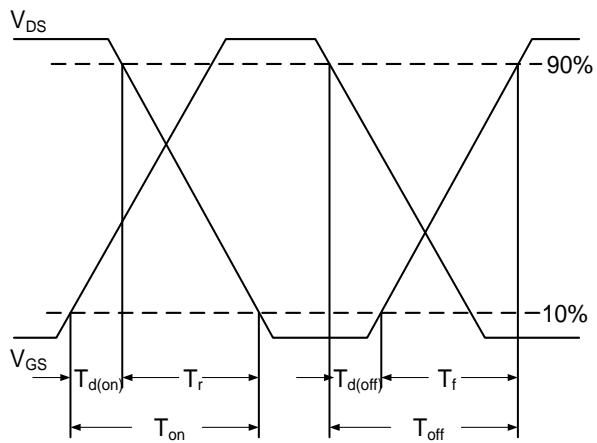
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-3.2	A
			---	---	-6.4	A
I_{SM}	Pulsed Source Current					
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{s}}=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V

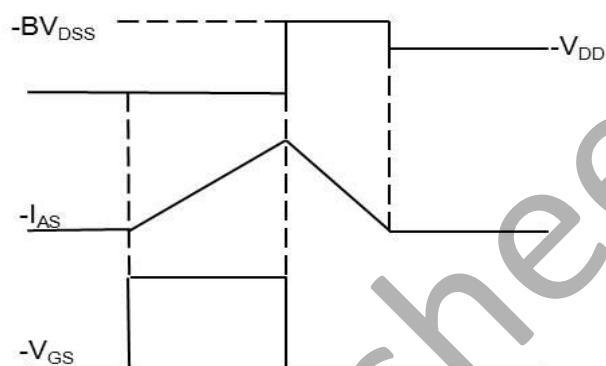
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{\text{DD}}=-25\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=-18\text{A}$, $R_{\text{G}}=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

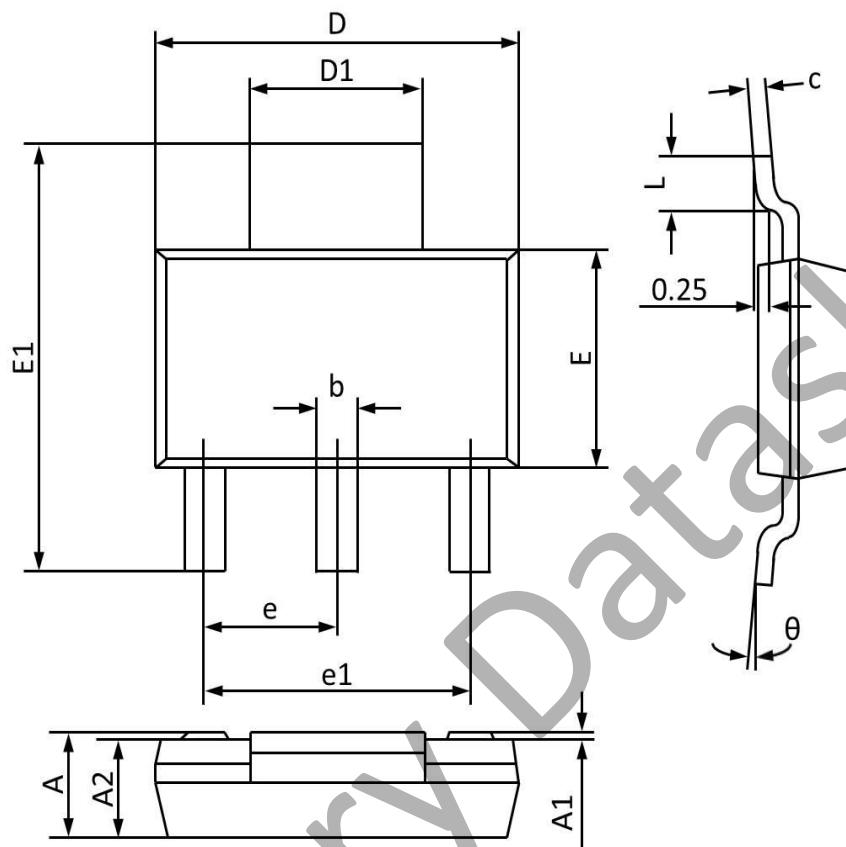

Fig.1 Continuous Drain Current vs. T_J

Fig.2 Normalized R_{DS(on)} vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

$$EAS = \frac{1}{2} L \times (-I_{AS})^2 \times \frac{-BV_{DSS}}{-BV_{DSS} - (-V_{DD})}$$


Fig.8 EAS Waveform

TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.800	1.520	0.071	0.060
A1	0.100	0.000	0.004	0.000
A2	1.700	1.500	0.067	0.059
b	0.820	0.660	0.032	0.026
c	0.350	0.250	0.014	0.010
D	6.400	6.200	0.252	0.244
D1	3.100	2.900	0.122	0.114
E	3.700	3.300	0.146	0.130
E1	7.070	6.830	0.278	0.269
e	2.30(BSC)		0.091(BSC)	
e1	4.700	4.500	0.185	0.177
L	1.150	0.900	0.045	0.035
θ	10°	0°	10°	0°